



Description

The HSU8048 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous rectification applications.

The HSU8048 meet the RoHS and Halogen-Free compliant product requirement, 100% EAS guaranteed with full function reliability approved.

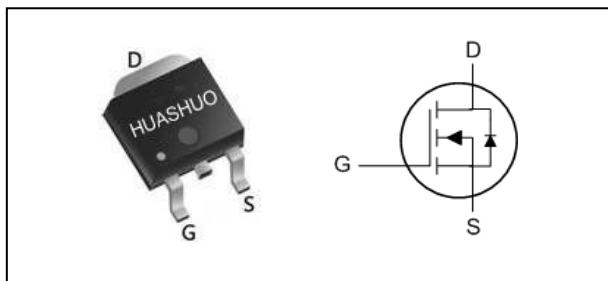
- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

N-Ch 80V Fast Switching MOSFETs

Product Summary

V _{DS}	80	V
R _{DS(ON),typ}	4.3	mΩ
I _D	48	A

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	80	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ 10V _{1,6}	48	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @ 10V _{1,6}	42.5	A
I _{DM}	Pulsed Drain Current ²	170	A
EAS	Single Pulse Avalanche Energy ³	57.8	mJ
I _{AS}	Avalanche Current	34	A
P _D @T _c =25°C	Total Power Dissipation ⁴	56	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.2	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80	---	---	V
R _{D(S)} (ON)	Static Drain-Source On-Resistance ₂	V _{GS} =10V , I _D =20A	---	4.3	6.5	mΩ
R _{D(S)} (ON)	Static Drain-Source On-Resistance ₂	V _{GS} =4.5V , I _D =20A	---	6.3	8.5	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	---	2.3	V
I _{bss}	Drain-Source Leakage Current	V _{DS} =64V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =64V , V _{GS} =0V , T _J =55°C	---	---	5	
I _{GS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
g _{fS}	Forward Transconductance	V _{DS} =5V , I _D =20A	---	75	---	S
R _G	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	0.5	---	Ω
Q _G	Total Gate Charge (10V)	V _{DS} =40V , V _{GS} =10V , I _D =20A	---	40	---	nC
Q _{GS}	Gate-Source Charge		---	7.2	---	
Q _{GD}	Gate-Drain Charge		---	6.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =40V , V _{GS} =10V , R _G =3Ω, I _D =20A	---	8.3	---	ns
T _r	Rise Time		---	4.2	---	
T _{d(off)}	Turn-Off Delay Time		---	36	---	
T _f	Fall Time		---	6.9	---	
C _{iss}	Input Capacitance	V _{DS} =40V , V _{GS} =0V , f=1MHz	---	2860	---	pF
C _{oss}	Output Capacitance		---	410	---	
C _{rss}	Reverse Transfer Capacitance		---	38	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current _{1,5}	V _G =V _D =0V , Force Current	---	---	48	A
V _{SD}	Diode Forward Voltage ₂	V _{GS} =0V , I _s =A , T _J =25°C	---	0.77	1.0	V
t _{rr}	Reverse Recovery Time	I _F =20A , dI/dt=100A/μs , T _J =25°C	---	27	---	nS
Q _{rr}	Reverse Recovery Charge		---	89	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=34A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.



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Typical Characteristics

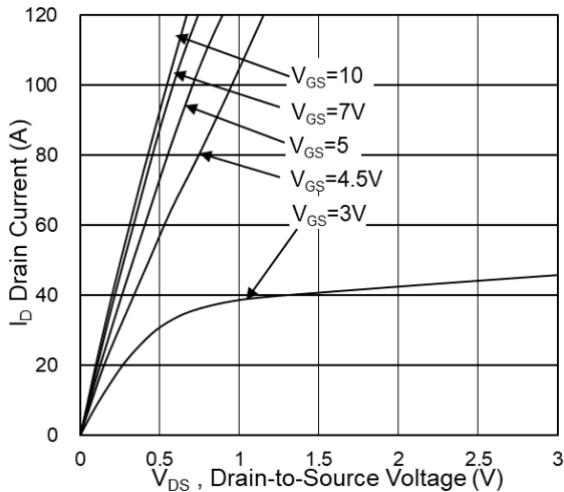


Fig.1 Typical Output Characteristics

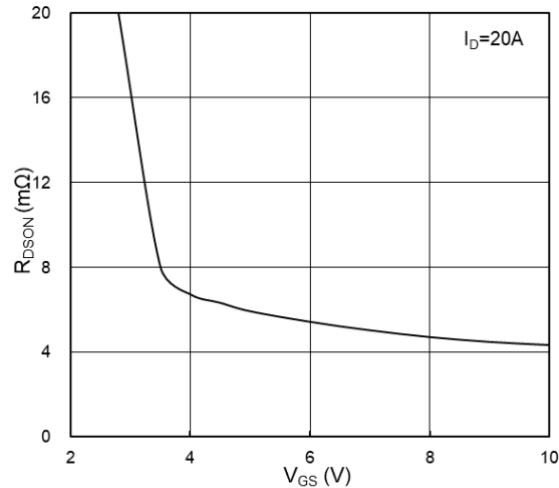


Fig.2 On-Resistance vs G-S Voltage

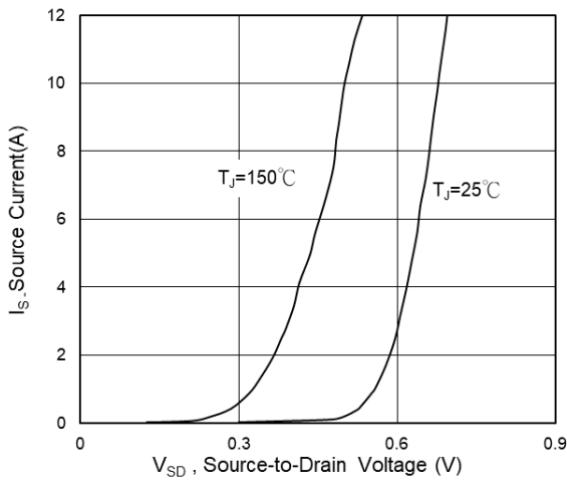


Fig.3 Source Drain Forward Characteristics

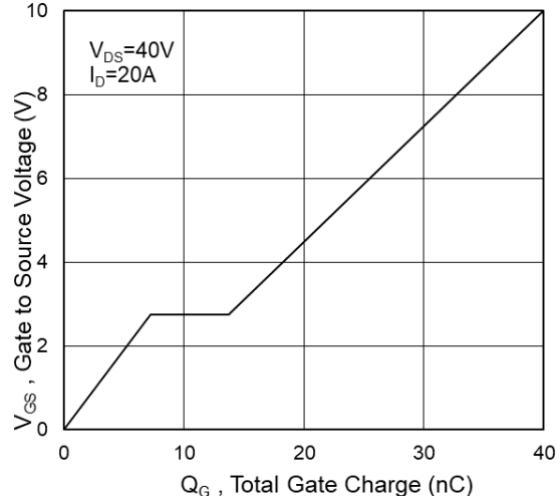


Fig.4 Gate-Charge Characteristics

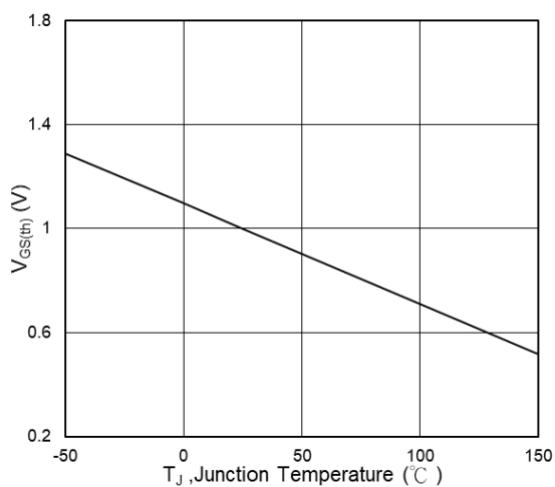


Fig.5 Normalized $V_{GS(th)}$ vs T_J

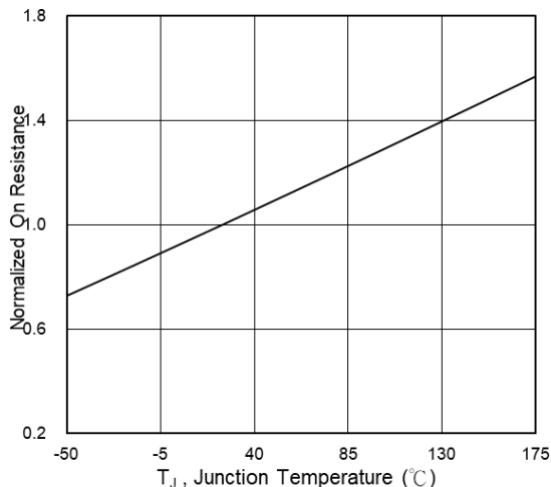


Fig.6 Normalized $R_{DS(on)}$ vs T_J



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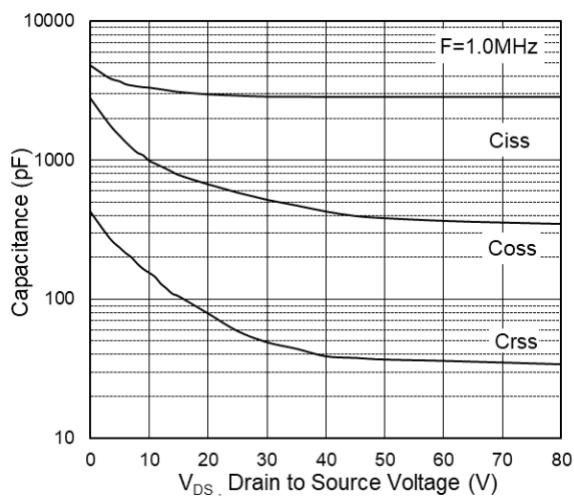


Fig.7 Capacitance

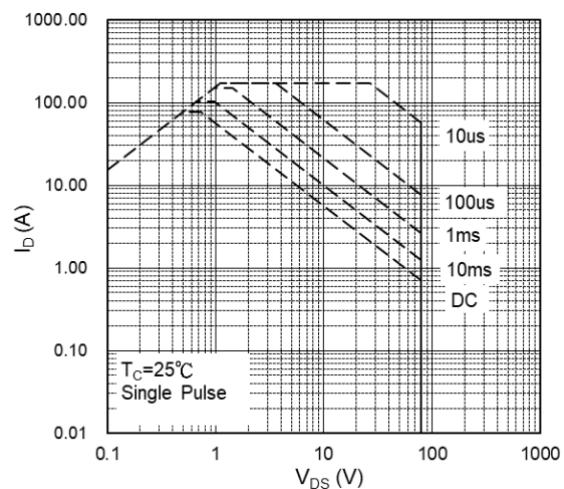


Fig.8 Safe Operating Area

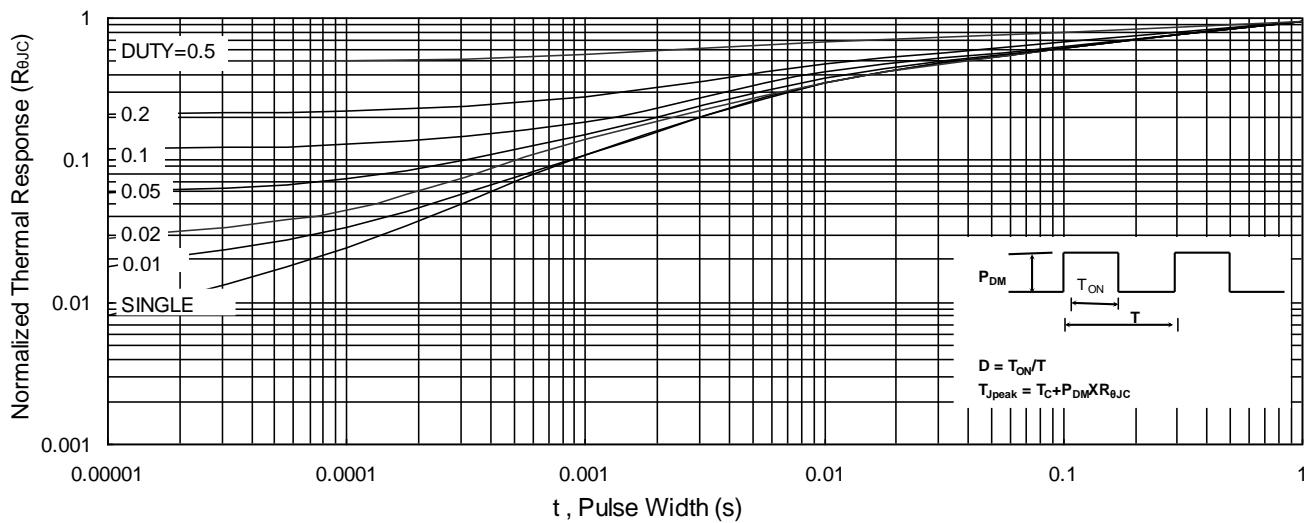


Fig.9 Normalized Maximum Transient Thermal Impedance

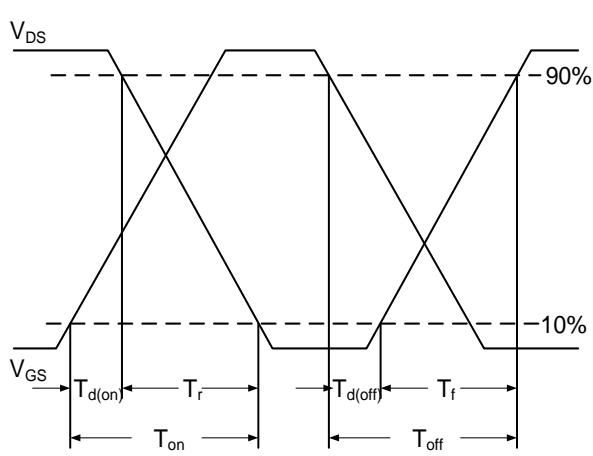


Fig.10 Switching Time Waveform

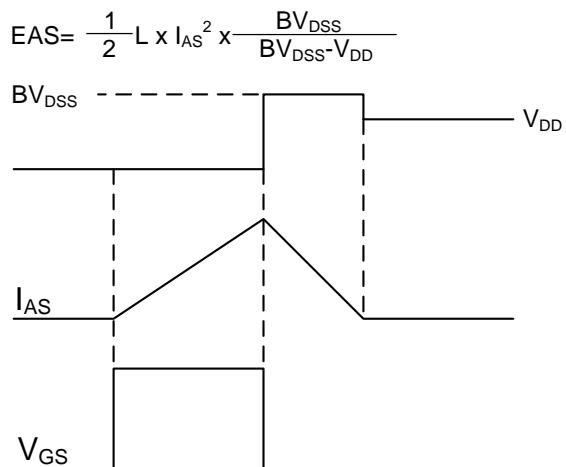


Fig.11 Unclamped Inductive Switching Waveform